

Search History

DATE: Thursday, September 16, 2004

<u>Set Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
			result set
	DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ		
<u>L34</u>	L33 and elongate slot	3	<u>L34</u>
<u>L33</u>	L31 and interposer	105	<u>L33</u>
<u>L32</u>	L31 and l1	3	<u>L32</u>
<u>L31</u>	die assembly	9914	<u>L31</u>
<u>L30</u>	L29 and @pd<20020109	12	<u>L30</u>
<u>L29</u>	L28 and l14	44	<u>L29</u>
<u>L28</u>	L27 and l10 and l17	126	<u>L28</u>
<u>L27</u>	L26 and l6	184	<u>L27</u>
<u>L26</u>	l23 and interposer	712	<u>L26</u>
<u>L25</u>	l23 and l2	242	<u>L25</u>
<u>L24</u>	L23 and l1	2	<u>L24</u>
<u>L23</u>	semiconductor package	21447	<u>L23</u>
<u>L22</u>	l19 and interposer	12	<u>L22</u>
<u>L21</u>	l19 and l2	7	<u>L21</u>
<u>L20</u>	L19 and l1	3	<u>L20</u>
<u>L19</u>	stacked die assembly	47	<u>L19</u>
<u>L18</u>	l16 and L17	21	<u>L18</u>
<u>L17</u>	flip chip	23197	<u>L17</u>
<u>L16</u>	L15 and @pd<20020109	30	<u>L16</u>
<u>L15</u>	l13 and L14	104	<u>L15</u>
<u>L14</u>	recess	1158916	<u>L14</u>
<u>L13</u>	L12 and l6	333	<u>L13</u>
<u>L12</u>	L11 and flexible	1526	<u>L12</u>
<u>L11</u>	L10 and interposer	3974	<u>L11</u>
<u>L10</u>	slot or via	3996157	<u>L10</u>
<u>L9</u>	L8 and l5	11	<u>L9</u>
<u>L8</u>	L7 and interposer	55	<u>L8</u>
<u>L7</u>	L6 and l2	736	<u>L7</u>
<u>L6</u>	conductive trace	11590	<u>L6</u>
<u>L5</u>	L4 and @pd<20020109	77	<u>L5</u>
<u>L4</u>	interposer and l2	256	<u>L4</u>
<u>L3</u>	l1 and L2	3	<u>L3</u>
<u>L2</u>	flexible substrate	18292	<u>L2</u>
<u>L1</u>	flexible film interposer or flexibple interposer	11	<u>L1</u>

END OF SEARCH HISTORY

9/16/04 Craig A. Thompson